

MC10EP35, MC100EP35

3.3V / 5V ECL JK Flip-Flop

The MC10/100EP35 is a higher speed/low voltage version of the EL35 JK flip-flop. The J/K data enters the master portion of the flip-flop when the clock is LOW and is transferred to the slave, and thus the outputs, upon a positive transition of the clock. The reset pin is asynchronous and is activated with a logic HIGH.

The 100 Series contains temperature compensation.

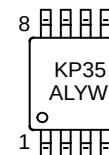
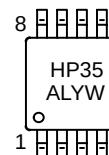
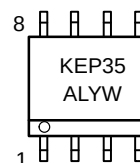
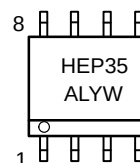
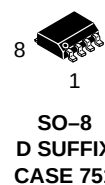
- 410 ps Propagation Delay
- Maximum Frequency > 3 GHz Typical
- PECL Mode Operating Range: $V_{CC} = 3.0\text{ V}$ to 5.5 V with $V_{EE} = 0\text{ V}$
- NECL Mode Operating Range: $V_{CC} = 0\text{ V}$ with $V_{EE} = -3.0\text{ V}$ to -5.5 V
- Open Input Default State
- Q Output Will Default LOW with Inputs Open or at V_{EE}



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MARKING DIAGRAMS*



H = MC10 L = Wafer Lot
K = MC100 Y = Year
A = Assembly Location W = Work Week

*For additional information, see Application Note AND8002/D

ORDERING INFORMATION

Device	Package	Shipping
MC10EP35D	SO-8	98 Units/Rail
MC10EP35DR2	SO-8	2500 Tape & Reel
MC100EP35D	SO-8	98 Units/Rail
MC100EP35DR2	SO-8	2500 Tape & Reel
MC10EP35DT	TSSOP-8	100 Units/Rail
MC10EP35DTR2	TSSOP-8	2500 Tape & Reel
MC100EP35DT	TSSOP-8	100 Units/Rail
MC100EP35DTR2	TSSOP-8	2500 Tape & Reel

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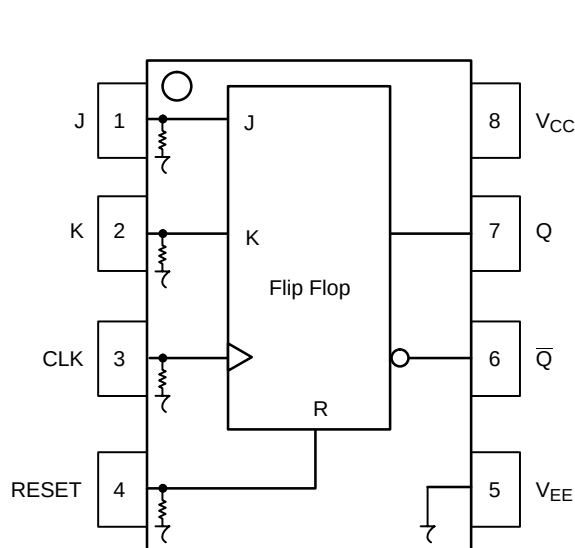


Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

PIN DESCRIPTION

PIN	FUNCTION
CLK*	ECL Clock Inputs
J*, K*	ECL Signal Inputs
RESET*	ECL Asynchronous Reset
Q, $\bar{Q}$	ECL Data Outputs
V _{CC}	Positive Supply
V _{EE}	Negative Supply

* Pins will default LOW when left open.

TRUTH TABLE

J	K	RESET	CLK	Q _{n+1}
L	L	L	Z	Q _n
L	H	L	Z	L
H	L	L	Z	H
H	H	L	Z	$\bar{Q}_n$
X	X	H	X	L

Z = LOW to HIGH Transition

ATTRIBUTES

Characteristics	Value
Internal Input Pulldown Resistor	75 k Ω
Internal Input Pullup Resistor	N/A
ESD Protection	Human Body Model Machine Model Charged Device Model
	> 4 kV > 200 V > 2 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1.)	Level 1
Flammability Rating Oxygen Index	UL-94 code V-0 A 1/8" 28 to 34
Transistor Count	77 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note AND8003/D.

MAXIMUM RATINGS (Note 2.)

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		6	V
V _{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-6	V
V _I	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	V _I ≤ V _{CC} V _I ≥ V _{EE}	6 -6	V V
I _{out}	Output Current	Continuous Surge		50 100	mA mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 SOIC 8 SOIC	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction to Case)	std bd	8 SOIC	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	8 TSSOP 8 TSSOP	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction to Case)	std bd	8 TSSOP	41 to 44	°C/W
T _{sol}	Wave Solder	<2 to 3 sec @ 248°C		265	°C

2. Maximum Ratings are those values beyond which device damage may occur.

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10EP DC CHARACTERISTICS, PECL $V_{CC} = 3.3\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 3.)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	30	40	50	30	40	50	30	40	50	mA
V_{OH}	Output HIGH Voltage (Note 4.)	2165	2290	2415	2230	2355	2480	2290	2415	2540	mV
V_{OL}	Output LOW Voltage (Note 4.)	1365	1490	1615	1430	1555	1680	1490	1615	1740	mV
V_{IH}	Input HIGH Voltage (Single Ended)	2090		2415	2155		2480	2215		2540	mV
V_{IL}	Input LOW Voltage (Single Ended)	1365		1690	1460		1755	1490		1815	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lfpm is maintained.

3. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.3 V to -2.2 V.

4. All loading with 50 ohms to V_{CC} -2.0 volts.

10EP DC CHARACTERISTICS, PECL $V_{CC} = 5.0\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 5.)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	30	40	50	30	40	50	30	40	50	mA
V_{OH}	Output HIGH Voltage (Note 6.)	3865	3940	4115	3930	4055	4180	3990	4115	4240	mV
V_{OL}	Output LOW Voltage (Note 6.)	3065	3190	3315	3130	3255	3380	3190	3315	3440	mV
V_{IH}	Input HIGH Voltage (Single Ended)	3790		4115	3855		4180	3915		4240	mV
V_{IL}	Input LOW Voltage (Single Ended)	3065		3390	3130		3455	3190		3515	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lfpm is maintained.

5. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +2.0 V to -0.5 V.

6. All loading with 50 ohms to V_{CC} -2.0 volts.

10EP DC CHARACTERISTICS, NECL $V_{CC} = 0\text{ V}$; $V_{EE} = -5.5\text{ V}$ to -3.0 V (Note 7.)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	30	40	50	30	40	50	30	40	50	mA
V_{OH}	Output HIGH Voltage (Note 8.)	-1135	-1010	-885	-1070	-945	-820	-1010	-885	-760	mV
V_{OL}	Output LOW Voltage (Note 8.)	-1935	-1810	-1685	-1870	-1745	-1620	-1810	-1685	-1560	mV
V_{IH}	Input HIGH Voltage (Single Ended)	-1210		-885	-1145		-820	-1085		-760	mV
V_{IL}	Input LOW Voltage (Single Ended)	-1935		-1610	-1870		-1545	-1810		-1485	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lfpm is maintained.

7. Input and output parameters vary 1:1 with V_{CC} .

8. All loading with 50 ohms to V_{CC} -2.0 volts.

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100EP DC CHARACTERISTICS, PECL $V_{CC} = 3.3\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 9.)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	30	40	50	30	40	50	30	40	50	mA
V_{OH}	Output HIGH Voltage (Note 10.)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V_{OL}	Output LOW Voltage (Note 10.)	1355	1480	1605	1355	1480	1605	1355	1480	1605	mV
V_{IH}	Input HIGH Voltage (Single Ended)	2075		2420	2075		2420	2075		2420	mV
V_{IL}	Input LOW Voltage (Single Ended)	1355		1675	1355		1675	1355		1675	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lfpm is maintained.

9. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.3 V to -2.2 V.

10. All loading with 50 ohms to V_{CC} -2.0 volts.

100EP DC CHARACTERISTICS, PECL $V_{CC} = 5.0\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 11.)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	30	40	50	30	40	50	30	40	50	mA
V_{OH}	Output HIGH Voltage (Note 12.)	3855	3980	4105	3855	3980	4105	3855	3980	4105	mV
V_{OL}	Output LOW Voltage (Note 12.)	3055	3180	3305	3055	3180	3305	3055	3180	3305	mV
V_{IH}	Input HIGH Voltage (Single Ended)	3775		4120	3775		4120	3775		4120	mV
V_{IL}	Input LOW Voltage (Single Ended)	3055		3375	3055		3375	3055		3375	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lfpm is maintained.

11. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +2.0 V to -0.5 V.

12. All loading with 50 ohms to V_{CC} -2.0 volts.

100EP DC CHARACTERISTICS, NECL $V_{CC} = 0\text{ V}$; $V_{EE} = -5.5\text{ V}$ to -3.0 V (Note 13.)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	30	40	50	30	40	50	30	40	50	mA
V_{OH}	Output HIGH Voltage (Note 14.)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
V_{OL}	Output LOW Voltage (Note 14.)	-1945	-1820	-1695	-1945	-1820	-1695	-1945	-1820	-1695	mV
V_{IH}	Input HIGH Voltage (Single Ended)	-1225		-880	-1225		-880	-1225		-880	mV
V_{IL}	Input LOW Voltage (Single Ended)	-1945		-1625	-1945		-1625	-1945		-1625	mV
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500 lfpm is maintained.

13. Input and output parameters vary 1:1 with V_{CC} .

14. All loading with 50 ohms to V_{CC} -2.0 volts.

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AC CHARACTERISTICS $V_{CC} = 0\text{ V}$; $V_{EE} = -3.0\text{ V}$ to -5.5 V or $V_{CC} = 3.0\text{ V}$ to 5.5 V ; $V_{EE} = 0\text{ V}$ (Note 15.)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{\max}$	Maximum Frequency (See Figure 2. $F_{\max}/\text{JITTER}$)		> 3			> 3			> 3		GHz
t_{PLH} , t_{PHL}	Propagation Delay to Output Differential R, CLK to Q, $\overline{Q}$	320	400	480	330	410	490	340	420	500	ps
t_{RR}	Reset Recovery	150	80		150	90		150	100		ps
t_S t_H	Setup Time Hold Time	150 150	50 50		150 150	50 50		150 150	80 80		ps
t_{PW}	Minimum Pulse width RESET	550	400		550	400		550	400		ps
t_{JITTER}	Cycle-to-Cycle Jitter (See Figure 2. $F_{\max}/\text{JITTER}$)		0.2	< 1		0.2	< 1		0.2	< 1	ps
t_r t_f	Output Rise/Fall Times (20% – 80%) Q, $\overline{Q}$	70	120	170	80	130	180	100	150	200	ps

15. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 ohms to $V_{CC}-2.0\text{ V}$.

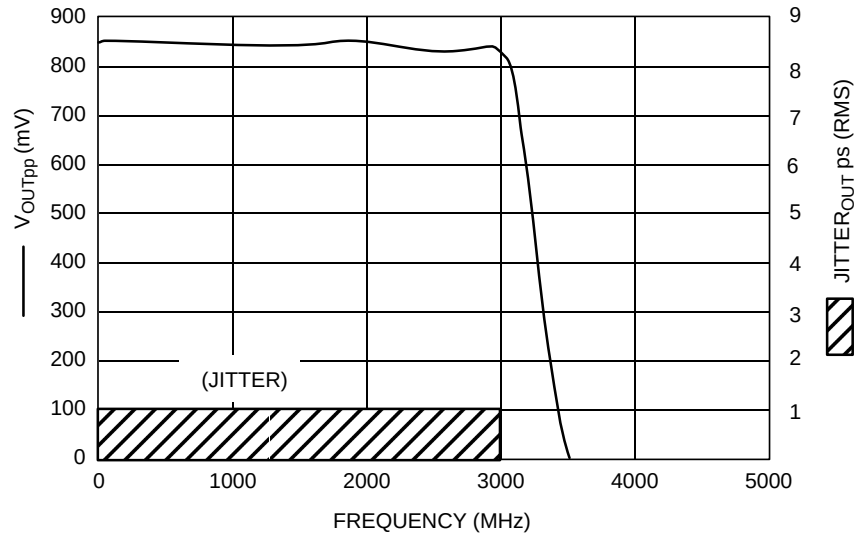


Figure 2. $F_{\max}/\text{Jitter}$

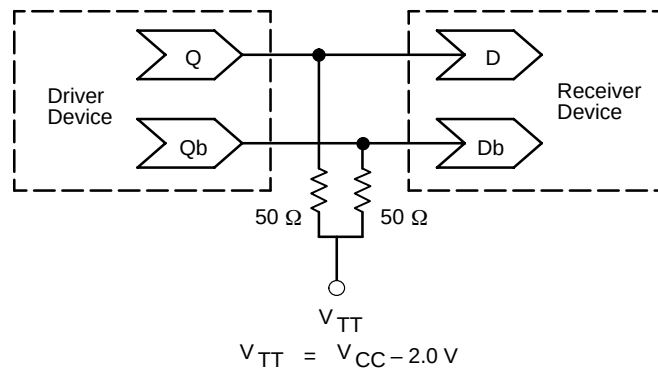


Figure 3. Typical Termination for Output Driver and Device Evaluation
(See Application Note AND8020 – Termination of ECL Logic Devices.)

Resource Reference of Application Notes

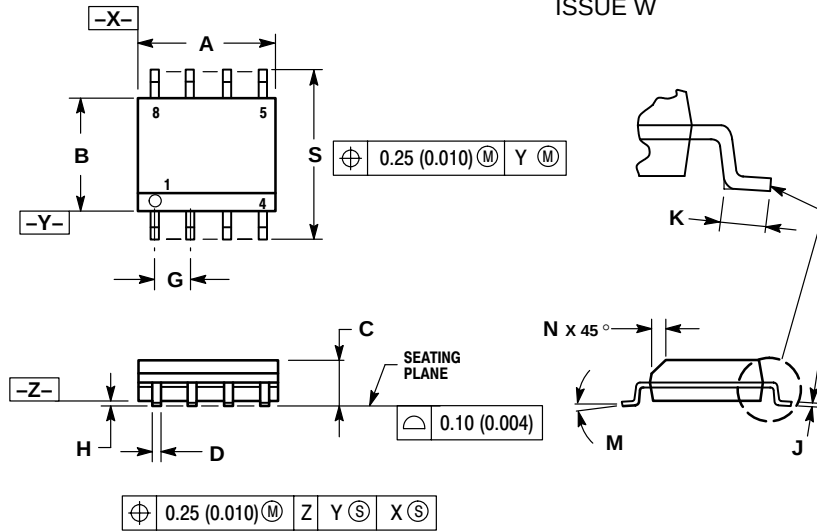
- AN1404** – ECLinPS Circuit Performance at Non-Standard V_{IH} Levels
- AN1405** – ECL Clock Distribution Techniques
- AN1406** – Designing with PECL (ECL at +5.0 V)
- AN1504** – Metastability and the ECLinPS Family
- AN1568** – Interfacing Between LVDS and ECL
- AN1650** – Using Wire-OR Ties in ECLinPS Designs
- AN1672** – The ECL Translator Guide
- AND8001** – Odd Number Counters Design
- AND8002** – Marking and Date Codes
- AND8009** – ECLinPS Plus Spice I/O Model Kit
- AND8020** – Termination of ECL Logic Devices

For an updated list of Application Notes, please see our website at <http://onsemi.com>.

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PACKAGE DIMENSIONS

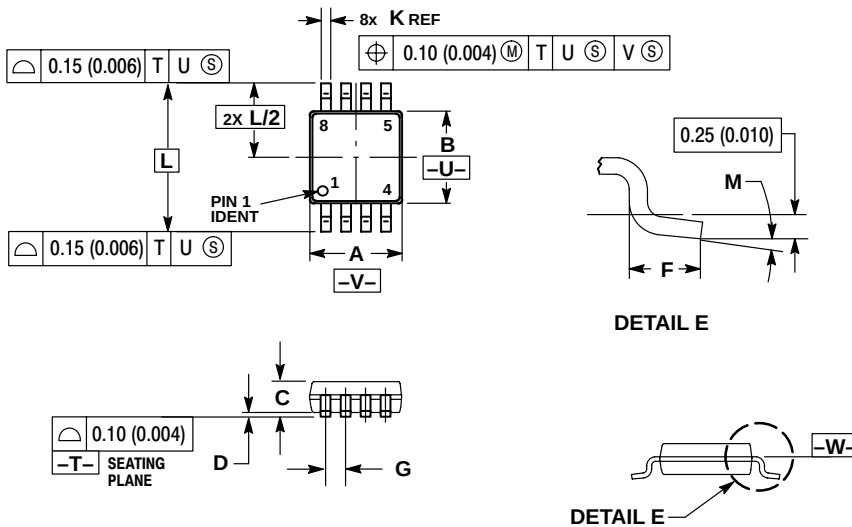
SO-8 D SUFFIX PLASTIC SOIC PACKAGE CASE 751-07 ISSUE W



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

TSSOP-8 DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948R-02 ISSUE A



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°

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